

MotionEngine™ Robotics

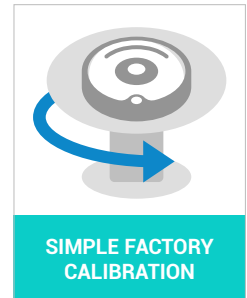
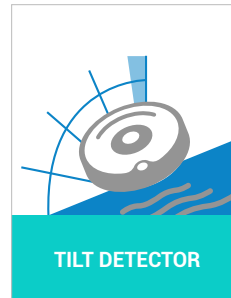
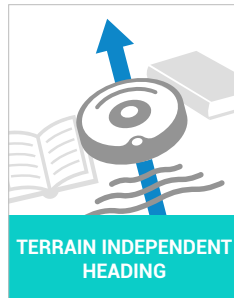
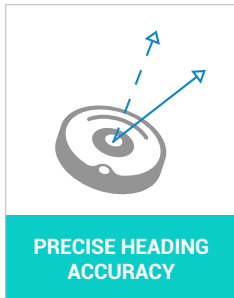
As the world becomes more connected, automated robots allow for an extra layer of ease and efficiency at home and in industrial applications. And the key to those applications is precise heading. If a robot doesn't move where it's designed to, it can't perform its tasks effectively.

With robotic-specific algorithms like low-drift heading, Interactive Calibration, and Simple Calibration, CEVA's Robotics package gets the most out of consumer grade MEMS, from the factory to the kitchen floor. These specialized capabilities are available on our FSP200 Sensor Hub - with support for multiple 6-axis sensors - to promote flexibility in design, manufacturing, and BOM cost.



FEATURE HIGHLIGHTS

- ✓ MotionEngine™ 6-Axis Sensor Fusion – Provides raw, calibrated and fused sensor orientation data with best in class heading accuracy and stability
- ✓ Choose Your Sensor – Low-cost MEMS sensors from top sensor vendors are supported
- ✓ Improved Performance – Working with our specialized Interactive Calibration software, top performance is achieved even with low-cost sensors
- ✓ Intelligent Power Management – Manages sensor states to conserve power without sacrificing quality of motion data
- ✓ Dynamic Calibration – Our algorithms constantly monitor changes in sensor performance and temperature during live operation to deliver the highest performance
- ✓ Suitable for Android, Linux, and Embedded Designs – Driver example code available for ease of integration
- ✓ Firmware Upgradeable – Embedded bootloader enables factory and in-field firmware updates
- ✓ Simplified UART Interface – Requires NO configuration; simply outputs data on power-up



ABOUT CEVA

CEVA is the leading licensor of wireless connectivity and smart sensing technologies. We offer Digital Signal Processors, AI processors, wireless platforms and complementary software for sensor fusion, image enhancement, computer vision, voice input and artificial intelligence, all of which are key enabling technologies for a smarter, connected world. We partner with semiconductor companies and OEMs worldwide to create power-efficient, intelligent and connected devices for a range of end markets, including mobile, consumer, automotive, robotics, industrial and IoT. Our ultra-low-power IPs include comprehensive DSP-based platforms for 5G baseband processing in mobile and infrastructure, advanced imaging and computer vision for any camera-enabled device and audio/voice/speech and ultra-low power always-on/sensing applications for multiple IoT markets. For sensor fusion, our Hillcrest Labs sensor processing technologies provide a broad range of sensor fusion software and IMU solutions for AR/VR, robotics, remote controls, and IoT. For artificial intelligence, we offer a family of AI processors capable of handling the complete gamut of neural network workloads, on-device. For wireless IoT, we offer the industry's most widely adopted IPs for Bluetooth (low energy and dual mode), Wi-Fi 4/5/6 (802.11n/ac/ax) and NB-IoT.

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